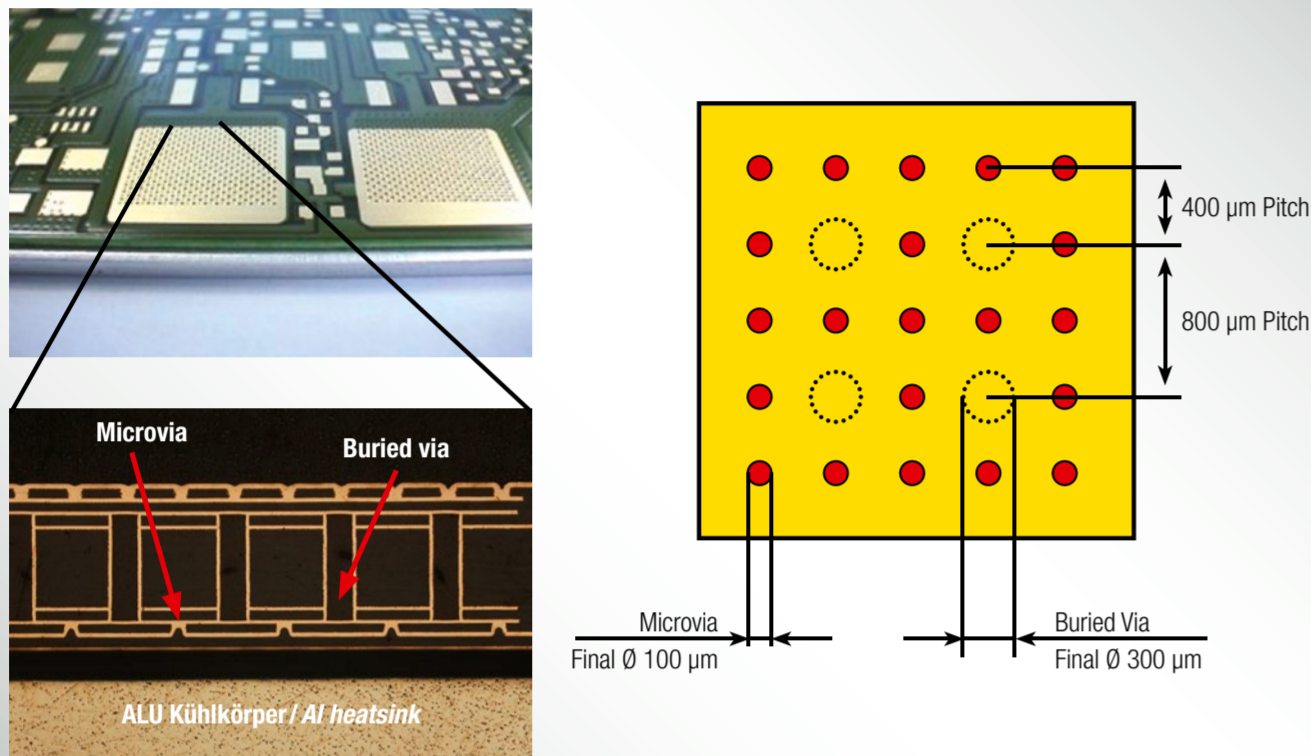


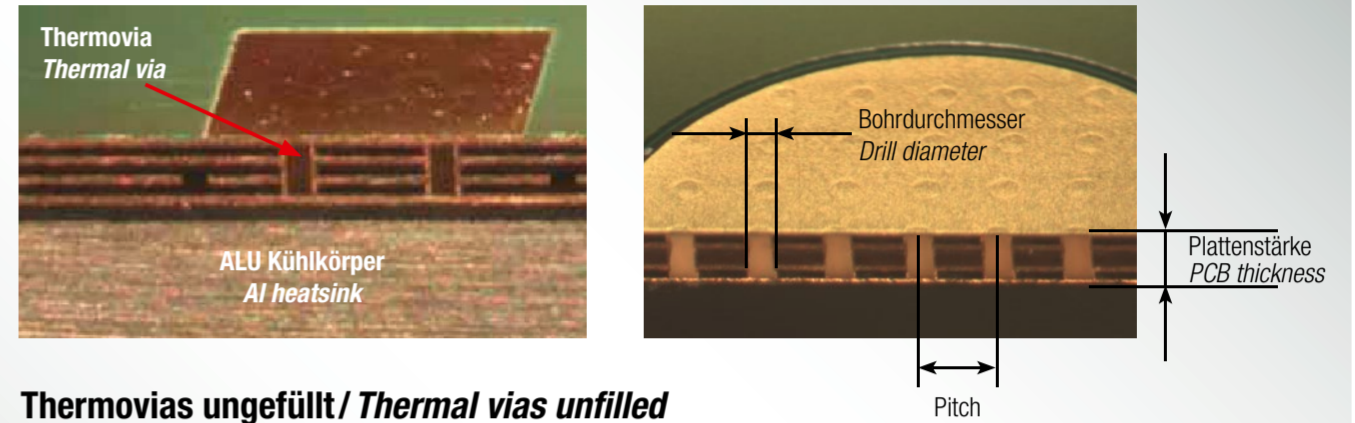
Wärmemanagement/ Thermal Management



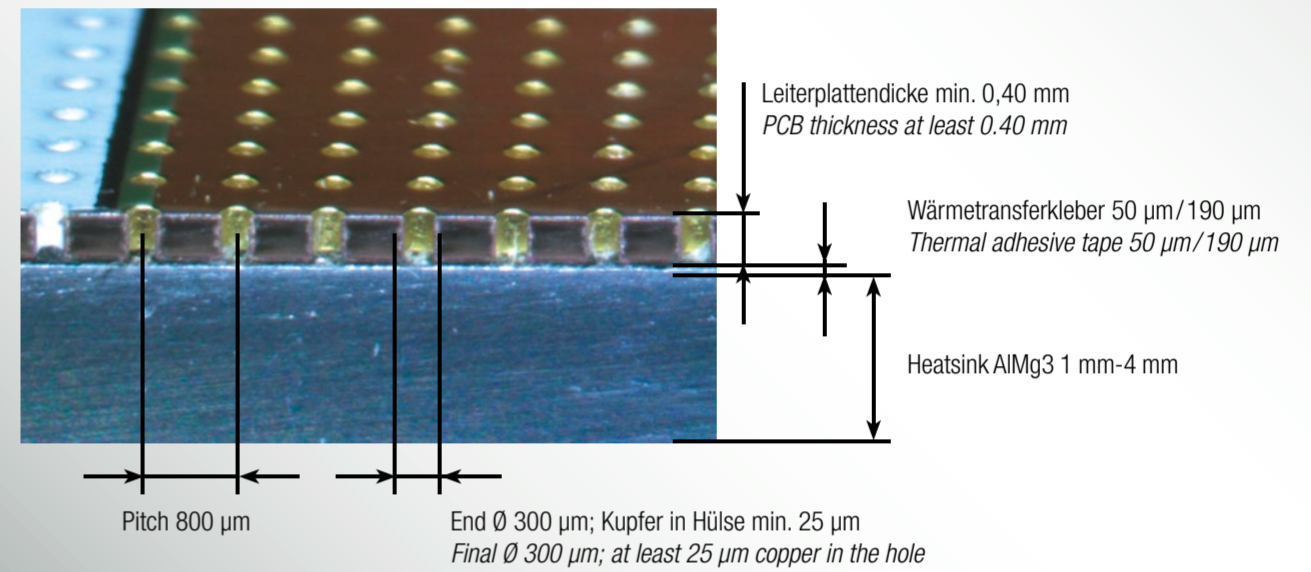
Kombination Microvia, Buried Via als Thermovias/ Combination microvia, buried via as thermal vias



Thermovias gefüllt (Via Filling) / Thermal vias filled (via filling)

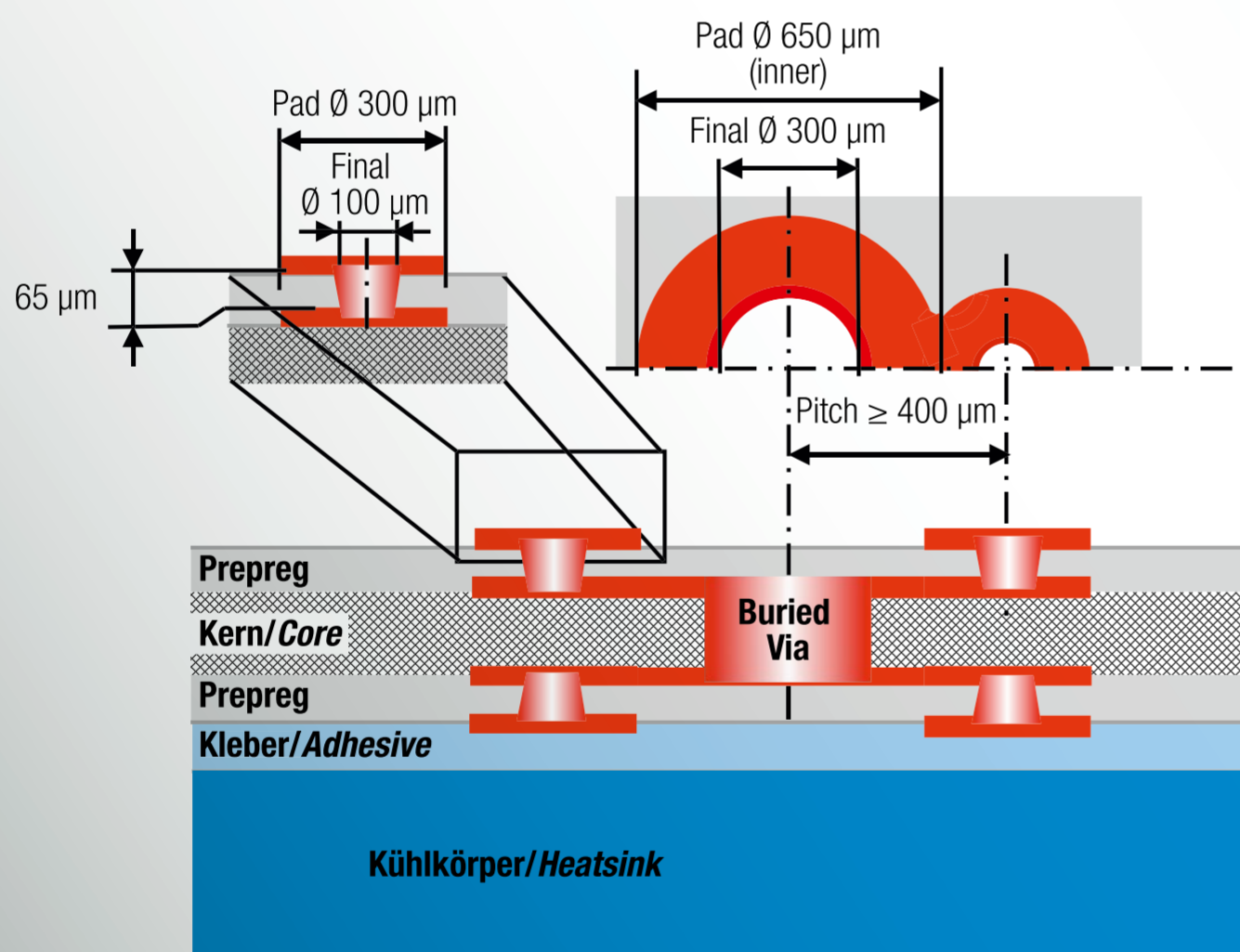


Thermovias ungefüllt / Thermal vias unfilled

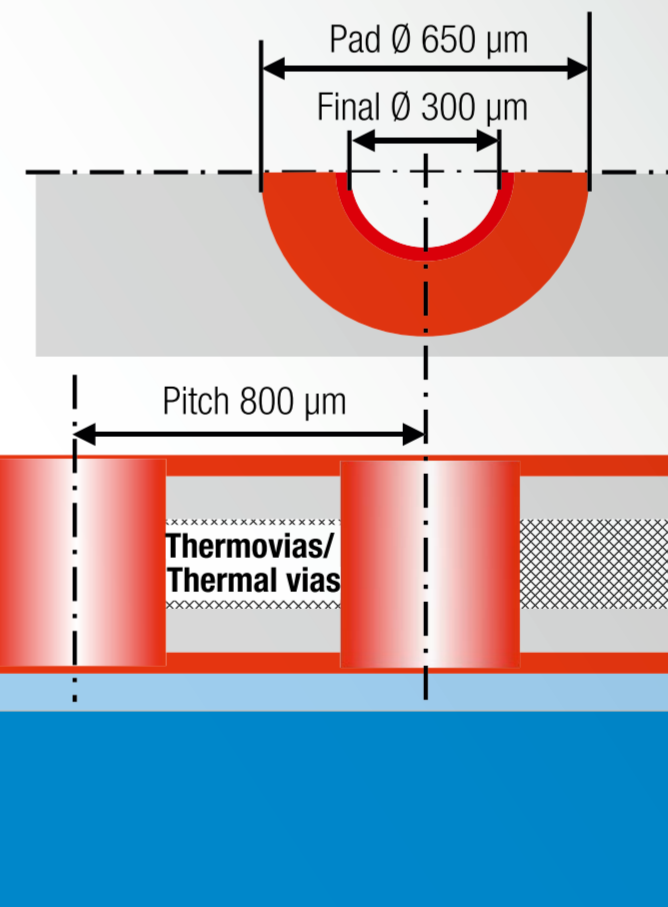


Standard Design Regeln / Standard Design Rules

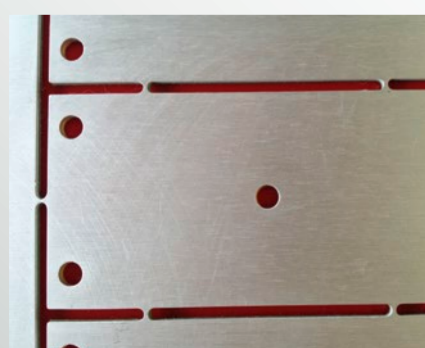
Microvias



Thermovias / Thermal vias

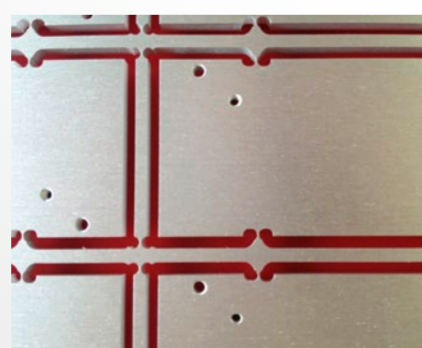


Sollbruchstellen Heatsink / Heatsink breaking points, micro edges



Positive Sollbruchstellen
Bruchstelle befindet sich im Fräskanal außerhalb der Leiterplattenkontur.

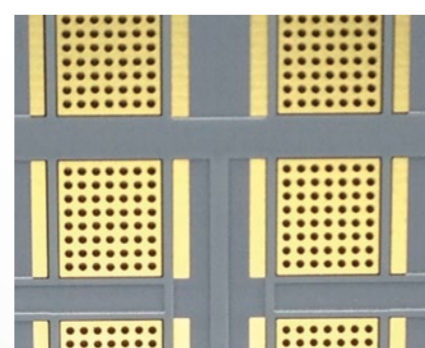
Positive micro edges
The breaking point is located in the rout path outside the PCB outline.



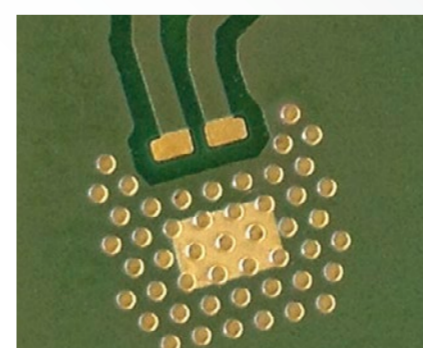
Negative Sollbruchstellen
Bruchstelle innerhalb der Leiterplattenkontur. Zusätzliche Zwischenstege zur Stabilität des Nutzens benötigt.

Negative micro edges
Breaking point inside the PCB outline. To ensure stability of the panel additional ribs are required.

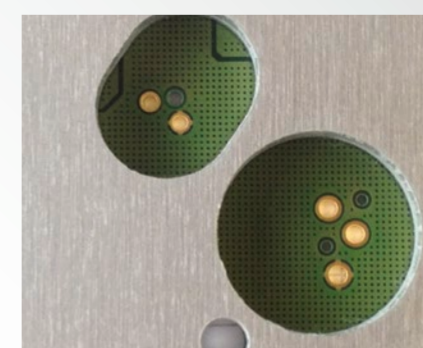
Designbeispiele / Scope for design



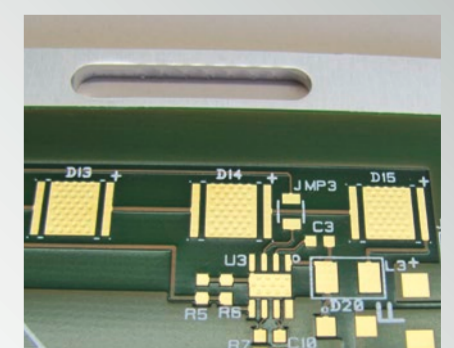
Thermovias im Pad/
Thermal vias in pad



Thermovias im Pad und außerhalb/
Thermal vias in pad and external



Ausbruch im Heatsink/
Cut-out in heatsink



Heatsink größer als Leiterplatte/
Heatsink larger than PCB